TPD4E6B06 4-Channel Bidirectional Low Capacitance ESD Protection Device With 15-kV Contact and Ultra-Low Clamping Voltage

1 Features

- IEC 61000-4-2 Level 4
  - ±15-kV Contact Discharge
  - ±15-kV Air Gap Discharge
- IEC 61000-4-5 (Surge): 3 A (8/20 µs)
- IO Capacitance: 4.8 pF (Typical)
- $R_{DYN}$: 0.75 Ω (Typical)
- DC Breakdown Voltage: ±6 V (Minimum)
- Ultra Low Leakage Current: 100 nA (Maximum)
- Clamping Voltage: 10 V (Maximum at $I_{PP} = 1$ A)
- Industrial Temperature Range: –40°C to +125°C
- Space Saving DPW Package (0.8 mm x 0.8 mm)

2 Applications

- Audio Lines
  - Microphone
  - Earphone
  - Speakerphone
- SD Interface
- SIM Interface
- Mobile Keyboard or Other Buttons
- Cell Phones
- eBook
- Portable Media Players
- Digital Camera
- Tablet PC
- Wearables

3 Description

The TPD4E6B06 is a four channel electrostatic discharge (ESD) protection device in an ultra small DPW package. It is the industry’s smallest 4-channel transient voltage suppressor (TVS) diode with a 0.48-mm pitch. This larger pitch helps save on printed-circuit board (PCB) manufacturing costs. The device provides IEC61000-4-2 compliance up to 15-kV contact discharge. It has an ESD clamp circuit with back-to-back diodes for bipolar-bidirectional signal support. The 4.8-pF (typical) line capacitance is suitable for a wide range of applications supporting data rates up to 700 MHz.

Device Information

<table>
<thead>
<tr>
<th>PART NUMBER</th>
<th>PACKAGE</th>
<th>BODY SIZE (NOM)</th>
</tr>
</thead>
<tbody>
<tr>
<td>TPD4E6B06</td>
<td>X2SON (4)</td>
<td>0.80 mm x 0.80 mm</td>
</tr>
</tbody>
</table>

(1) For all available packages, see the orderable addendum at the end of the data sheet.
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4 Revision History
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision B (February 2017) to Revision C Page
• Added “Power Supply Recommendations” section ................................................................. 12

Changes from Revision A (December 2015) to Revision B Page
• Changed the value of R_{DYN} from 0.75 and 0.65 to 0.45 and 0.42 respectively, in the Electrical Characteristics table ......... 5

Changes from Original (May 2014) to Revision A Page
• Updated the Handling Ratings table into an ESD Ratings table and moved T_{stg} to the Absolute Maximum Ratings table ... 4
• Added new note to Absolute Maximum Ratings table .................................................................. 4
• Added frequency test condition to IO capacitance in the Electrical Characteristics table ...................... 5
• Added Community Resources .................................................................................................. 14
5 Pin Configuration and Functions

DPW Package
5-Pin X2SON
Bottom View

<table>
<thead>
<tr>
<th>PIN</th>
<th>I/O</th>
<th>DESCRIPTION</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>IO1</td>
<td>IO ESD protected line</td>
</tr>
<tr>
<td>2</td>
<td>IO2</td>
<td>IO ESD protected line</td>
</tr>
<tr>
<td>3</td>
<td>IO3</td>
<td>IO ESD protected line</td>
</tr>
<tr>
<td>4</td>
<td>IO4</td>
<td>IO ESD protected line</td>
</tr>
<tr>
<td>5</td>
<td>GND</td>
<td>— Ground</td>
</tr>
</tbody>
</table>
6 Specifications

6.1 Absolute Maximum Ratings
over operating free-air temperature range (unless otherwise noted)\(^{(1)}\)\(^{(2)}\)\(^{(3)}\)

<table>
<thead>
<tr>
<th></th>
<th>MIN</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Peak pulse IEC 61000-4-5 Current ((t_p = 8/20) µs)(^{(4)})</td>
<td>3</td>
<td></td>
<td>A</td>
</tr>
<tr>
<td>IEC 61000-4-5 Power ((t_p = 8/20) µs)(^{(4)})</td>
<td>40</td>
<td></td>
<td>W</td>
</tr>
<tr>
<td>Operating temperature</td>
<td>−40</td>
<td>125</td>
<td>°C</td>
</tr>
<tr>
<td>Storage temperature</td>
<td>−65</td>
<td>155</td>
<td>°C</td>
</tr>
</tbody>
</table>

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) Absolute maximum ratings apply over recommended junction temperature range.

(3) Voltages are with respect to GND unless otherwise noted.

(4) Measured at 25°C.

6.2 ESD Ratings

<table>
<thead>
<tr>
<th></th>
<th>VALUE</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>(V_{\text{ESD}}) Electrostatic discharge</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins(^{(1)})</td>
<td>±2000</td>
<td>V</td>
</tr>
<tr>
<td>Charged device model (CDM), per JEDEC specification JESD22-C101, all pins(^{(2)})</td>
<td>±500</td>
<td>V</td>
</tr>
</tbody>
</table>

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Pins listed as 2 kV may actually have higher performance.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Pins listed as 500 V may actually have higher performance.

6.3 Recommended Operating Conditions
over operating free-air temperature range (unless otherwise noted)

<table>
<thead>
<tr>
<th></th>
<th>MIN</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>(V_{\text{IO}}) Input pin voltage</td>
<td>−5.5</td>
<td>5.5</td>
<td>V</td>
</tr>
<tr>
<td>(T_A) Operating free-air temperature</td>
<td>−40</td>
<td>125</td>
<td>°C</td>
</tr>
</tbody>
</table>

6.4 Thermal Information

<table>
<thead>
<tr>
<th>THERMAL METRIC(^{(1)})</th>
<th>TPD4E6B06</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>DPW (X2SON) 5 PINS</td>
<td></td>
<td></td>
</tr>
<tr>
<td>(R_{\text{UA}}) Junction-to-ambient thermal resistance</td>
<td>291.8</td>
<td>°C/W</td>
</tr>
<tr>
<td>(R_{\text{UJC(top)}}) Junction-to-case (top) thermal resistance</td>
<td>224.2</td>
<td>°C/W</td>
</tr>
<tr>
<td>(R_{\text{UB}}) Junction-to-board thermal resistance</td>
<td>245.8</td>
<td>°C/W</td>
</tr>
<tr>
<td>(\psi_{\text{JT}}) Junction-to-top characterization parameter</td>
<td>31.4</td>
<td>°C/W</td>
</tr>
<tr>
<td>(\psi_{\text{JB}}) Junction-to-board characterization parameter</td>
<td>245.6</td>
<td>°C/W</td>
</tr>
<tr>
<td>(R_{\text{UJC(bot)}}) Junction-to-case (bottom) thermal resistance</td>
<td>195.4</td>
<td>°C/W</td>
</tr>
</tbody>
</table>

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.
### 6.5 Electrical Characteristics

$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$ (unless otherwise specified)

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITION</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{RWM}$</td>
<td>Reverse stand-off voltage $I_{IO} = 10 \mu\text{A}$</td>
<td>$-5.5$</td>
<td>$5.5$</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>$V_{BRF}$</td>
<td>Break-down voltage $I_{IO \text{ to GND}} = 1 \text{mA}$</td>
<td>$6$</td>
<td></td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>$V_{BRR}$</td>
<td>Break-down voltage $I_{\text{GND to IO}} = 1 \text{mA}$</td>
<td>$6$</td>
<td></td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>$I_{\text{LEAK}}$</td>
<td>Leakage current $V_{IO} = 5 \text{V}$</td>
<td>$100$</td>
<td>nA</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$V_{\text{CLAMP}}$</td>
<td>Clamp voltage with ESD strike $I = 1 \text{A, IO to GND, 8/20 \mu\text{s}}^{(1)}$</td>
<td>$10$</td>
<td></td>
<td>V</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I = 5 \text{A, IO to GND, 8/20 \mu\text{s}}^{(1)}$</td>
<td>$13$</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I = 1 \text{A, IO to GND, 8/20 \mu\text{s}}^{(1)}$</td>
<td>$9$</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I = 5 \text{A, IO to GND, 8/20 \mu\text{s}}^{(1)}$</td>
<td>$13$</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>$R_{\text{DYN}}$</td>
<td>Dynamic resistance Any IO to GND pin$^{(2)}$</td>
<td>$0.45$</td>
<td></td>
<td>$\Omega$</td>
<td></td>
</tr>
<tr>
<td></td>
<td>GND to any IO pin$^{(2)}$</td>
<td>$0.42$</td>
<td></td>
<td>$\Omega$</td>
<td></td>
</tr>
<tr>
<td>$C_L$</td>
<td>IO capacitance $V_{IO} = 2.5 \text{V; } f = 10 \text{MHz}$</td>
<td>$4.8$</td>
<td></td>
<td>$7 \text{pF}$</td>
<td></td>
</tr>
</tbody>
</table>

(1) Non-repetitive current pulse 8/20 $\mu\text{s}$ exponentially decaying waveform according to IEC61000-4-5.
(2) Extraction of RDYN using least squares fit of TLP characteristics between $I = 10 \text{A}$ and $I = 20 \text{A}$. 

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Product Folder Links: TPD4E6B06
### 6.6 Typical Characteristics

<table>
<thead>
<tr>
<th>Figure 1. IEC 61000-4-2 Clamping Voltage, 8-kV Contact</th>
</tr>
</thead>
<tbody>
<tr>
<td>Voltage (V) vs. Time (ns)</td>
</tr>
<tr>
<td>RDYN = 0.45 Ω</td>
</tr>
<tr>
<td>t\text{PW} = 100 ns*</td>
</tr>
<tr>
<td>t\text{RISE} = 10 ns*</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Figure 2. IEC 61000-4-2 Clamping Voltage, −8-kV Contact</th>
</tr>
</thead>
<tbody>
<tr>
<td>Voltage (V) vs. Time (ns)</td>
</tr>
<tr>
<td>RDYN = 0.42 Ω</td>
</tr>
<tr>
<td>t\text{PW} = 100 ns*</td>
</tr>
<tr>
<td>t\text{RISE} = 10 ns*</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Figure 3. TLP, t\text{PW} = 100 ns, t\text{RISE} = 10 ns, IO to GND</th>
</tr>
</thead>
<tbody>
<tr>
<td>Current (A) vs. Voltage (V)</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Figure 4. TLP, t\text{PW} = 100 ns, t\text{RISE} = 10 ns, GND to IO</th>
</tr>
</thead>
<tbody>
<tr>
<td>Current (A) vs. Voltage (V)</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Figure 5. IV Curve</th>
</tr>
</thead>
<tbody>
<tr>
<td>Current (A) vs. Voltage (V)</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Figure 6. Surge Curves, IO to GND</th>
</tr>
</thead>
<tbody>
<tr>
<td>Current vs. Time (µs)</td>
</tr>
</tbody>
</table>

*Note: t\text{PW} and t\text{RISE} refer to pulse width and rise time, respectively.*
Typical Characteristics (continued)

Figure 7. Surge Curves, GND to IO

Figure 8. Capacitance

Figure 9. Insertion Loss
7 Detailed Description

7.1 Overview
The TPD4E6B06 is a four channel ESD Protection device in an ultra small DPW package. It is the industry’s smallest 4-CH ESD protection device with 0.48-mm pitch. This larger pitch helps save on PCB manufacturing costs. The device provides IEC61000-4-2 compliance up to 15-kV contact discharge. It has an ESD clamp circuit with back-to-back diodes for bipolar/bidirectional signal support. The 4.8-pF (Typical) line capacitance is suitable for a wide range of applications supporting frequencies up to 700 MHz.

7.2 Functional Block Diagram

7.3 Feature Description

7.3.1 IEC 61000-4-2 Level 2 ESD Protection
The IO pins can withstand ESD events up to ±15-kV contact and ±15-kV air. An ESD-surge clamp diverts the current to ground.

7.3.2 IEC 61000-4-5 Surge Protection
The IO pins can withstand surge events up to 3 A and 40 W (8/20 µs waveform). An ESD-surge clamp diverts this current to ground.

7.3.3 IO Capacitance
The capacitance between any IO pin to ground is 4.8 pF (typical). This capacitance supports frequencies up to 700 MHz.

7.3.4 $R_{DYN}$
The low $R_{DYN}$ of 0.75 Ω (typical) allows for lower clamping voltages.

7.3.5 DC Breakdown Voltage
The DC breakdown voltage of any IO pin is a minimum of ±6 V. This ensures that sensitive equipment is protected from surges above the reverse standoff voltage of ±5.5 V (minimum).

7.3.6 Ultra-Low Leakage Current
The IO pins feature an ultra-low leakage current of 100 nA (maximum) with a bias of 2.5 V.
Feature Description (continued)

7.3.7 Clamping Voltage
The IO pins feature an ESD clamp capable of clamping the voltage to 10 V (IO to GND) or 9 V (GND to IO) of IEC61000-4-5 surge when $I_{pp} = 1\ A$.

7.3.8 Industrial Temperature Range
This device features an industrial operating range of $-40^\circ\text{C}$ to $+125^\circ\text{C}$.

7.3.9 Space Saving DPW Package
The small 0.8 mm × 0.8 mm package size saves board space and makes it easy to add ESD protection.

7.4 Device Functional Modes
The TPD4E6B06 is a passive integrated circuit that triggers when voltages are above $V_{BRF}$ or $V_{BRR}$. During ESD events, voltages as high as ±15 kV (air) can be directed to ground via the internal diode network. Once the voltages on the protected line fall below the trigger levels of the TPD4E6B06 (usually within 10s of nano-seconds) the device reverts to passive.
8 Application and Implementation

NOTE
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI’s customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The TPD4E6B06 is a diode array type TVS. These low capacitance types of TVSs are typically used to provide a path to ground for dissipating ESD events on hi speed signal lines between a human interface connector and a system. During high voltage ESD strikes, the device clamps to a safe voltage level to protect the system.

The typical application of the TPD4E6B06 is to be placed in between the connector and the system. The low capacitance of the TPD4E6B06 gives flexibility in the end application, as it can be used on many different high speed interfaces.

8.2 Typical Application

8.2.1 Design Requirements

Table 1 shows the design parameters.

<table>
<thead>
<tr>
<th>DESIGN PARAMETER</th>
<th>EXAMPLE VALUE</th>
</tr>
</thead>
<tbody>
<tr>
<td>Signal range on data lines</td>
<td>–5.5 V to 5.5 V</td>
</tr>
<tr>
<td>Operating frequency</td>
<td>Up to 700 MHz</td>
</tr>
</tbody>
</table>

8.2.2 Detailed Design Procedure

The designer needs to know the following:
- Signal range on all the protected lines
- Operating frequency

8.2.2.1 Signal Range

The TPD4E6B06 has 4 protection channels for signal lines. Any I/O supports a signal range of –5.5 V to 5.5 V.

8.2.2.2 Operating Frequency

The TPD4E6B06 has 4.8 pF of capacitance (Typical), supporting up to 700 MHz frequencies.
8.2.3 Application Curve

Figure 11. Insertion Loss (Any IO to GND)
9 Power Supply Recommendations

The TPD4E6B06 is a passive TVS diode-based ESD protection device, so there is no need to power it. Ensure that the maximum voltage specifications for each pin are not violated.

10 Layout

10.1 Layout Guidelines

- Place the device as close to the connector as possible.
  - EMI during an ESD event can couple from the trace being struck to other nearby unprotected traces, resulting in early system failures.
  - The PCB designer must minimize the possibility of EMI coupling by keeping any unprotected traces away from the protected traces which are between the TVS and the connector.
- Route the protected traces as straight as possible.
- Eliminate any sharp corners on the protected traces between the TVS and the connector by using rounded corners with the largest radii possible.
  - Electric fields tend to build up on corners, increasing EMI coupling.

10.2 Layout Examples

Figure 12. Single Layer Routing

= VIA to GND Plane

1
2
3
4

Figure 12. Single Layer Routing
Layout Examples (continued)

Figure 13. Double Layer Routing
11 Device and Documentation Support

11.1 Documentation Support

11.1.1 Related Documentation
For related documentation, see the following:
• Reading and Understanding an ESD Protection Datasheet
• ESD Layout Guide

11.2 Receiving Notification of Documentation Updates
To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on Alert me to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

11.3 Community Resources
The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community  
Ti's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support  
Ti's Design Support Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.4 Trademarks
E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

11.5 Electrostatic Discharge Caution
These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.6 Glossary
SLYZ022 — Ti Glossary.
This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information
The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
4. The size and shape of this feature may vary.
5. Features may not exist. Recommend use of pin 1 marking on top of package for orientation purposes.
EXAMPLE BOARD LAYOUT

DPW0004A          X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

NOTES: (continued)

6. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
7. Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
### PACKAGING INFORMATION

<table>
<thead>
<tr>
<th>Orderable Device</th>
<th>Status</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>Package Qty</th>
<th>Eco Plan</th>
<th>Lead/Ball Finish</th>
<th>MSL Peak Temp</th>
<th>Op Temp (°C)</th>
<th>Device Marking</th>
<th>Samples</th>
</tr>
</thead>
<tbody>
<tr>
<td>TPD4E6B06DPWR</td>
<td>ACTIVE</td>
<td>X2SON</td>
<td>DPW</td>
<td>4</td>
<td>3000</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>NIPDAU</td>
<td>Level-1-260C-UNLIM</td>
<td>-40 to 125</td>
<td>(B1, B5)</td>
<td></td>
</tr>
</tbody>
</table>

(1) The marketing status values are defined as follows:

**ACTIVE**: Product device recommended for new designs.

**LIFEBUY**: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW**: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE**: TI has discontinued the production of the device.

(2) **RoHS**: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt**: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green**: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) **MSL, Peak Temp.** - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) **Lead/Ball Finish** - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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## TAPE AND REEL INFORMATION

<table>
<thead>
<tr>
<th>Device</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>SPQ</th>
<th>Reel Diameter (mm)</th>
<th>Reel Width W1 (mm)</th>
<th>A0 (mm)</th>
<th>B0 (mm)</th>
<th>K0 (mm)</th>
<th>P1 (mm)</th>
<th>W (mm)</th>
<th>Pin1 Quadrant</th>
</tr>
</thead>
<tbody>
<tr>
<td>TPD4E6B06DPWR</td>
<td>X2SON</td>
<td>DPW</td>
<td>4</td>
<td>3000</td>
<td>180.0</td>
<td>9.5</td>
<td>0.94</td>
<td>0.94</td>
<td>0.5</td>
<td>2.0</td>
<td>8.0</td>
<td>Q1</td>
</tr>
</tbody>
</table>

*All dimensions are nominal.

**Dimensions and Definitions:**
- **A0**: Dimension designed to accommodate the component width
- **B0**: Dimension designed to accommodate the component length
- **K0**: Dimension designed to accommodate the component thickness
- **W**: Overall width of the carrier tape
- **P1**: Pitch between successive cavity centers
### TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

<table>
<thead>
<tr>
<th>Device</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>SPQ</th>
<th>Length (mm)</th>
<th>Width (mm)</th>
<th>Height (mm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>TPD4E6B06DPWR</td>
<td>X2SON</td>
<td>DPW</td>
<td>4</td>
<td>3000</td>
<td>184.0</td>
<td>184.0</td>
<td>19.0</td>
</tr>
</tbody>
</table>
Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

2. This drawing is subject to change without notice.

3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

4. The size and shape of this feature may vary.

5. Features may not exist. Recommend use of pin 1 marking on top of package for orientation purposes.
6. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

7. Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
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